MGV252010S1R0M-10

PHYSICAL DIMENSIONS:

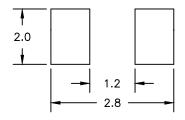
A 2.50 ± 0.20

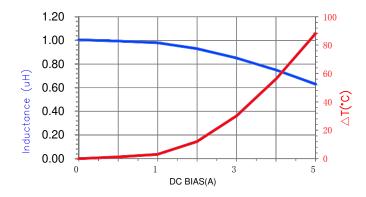
B 2.00 ± 0.20

C 1.00 Max.

 $D = 0.60 \pm 0.30$

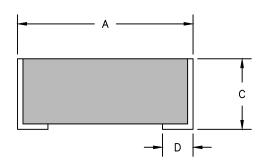
LAND PATTERNS FOR REFLOW SOLDERING



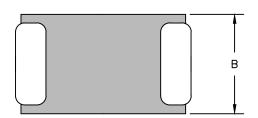


ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max	
INDUCTANCE (uH) L @ 1MHz/1mA ±20%	0.80	1.00	1.20	
DCR (Ω)		0.041	0.052	
Saturation Current Isat (A)		4.40	4.00	
Heating Current Irms (A)		3.40	3.10	







NOTES:

- 1. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. OPERATING TEMPERATURE RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$.
- 4. STORAGE TEMPERATURE RANGE: -50° C $\sim +125^{\circ}$ C.
- 5. ISat MEANS THAT MAX DC CURRENT WILL CAUSE A PROXIMATELY 30% INDUCTANCE REDUCTION FROM INITIAL VALUE.
- 6. Irms MEANS THAT MAX DC CURRENT WILL CAUSE PROXIMATELY 40°C TEMPERATURE RISE FROM 25±5°C AMBIENT.

DIMENSIONS ARE IN mm.		This print is the property of Laird							
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